

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A multilayer printed wiring board ~~having~~ comprising:
an interlayer insulating layer and a conductor layer formed on a core substrate, the
~~conductor~~ conductor layer being electrically connected through a via hole, ~~characterized in~~
~~that~~

wherein a thickness of the conductor layer on said core substrate is larger than a
thickness of the conductor layer on the interlayer insulating layer.

Claim 2 (Currently Amended): A multilayer printed wiring board ~~having~~ comprising:
an interlayer insulating layer and a conductor layer formed on a core substrate, the
conductor layer being electrically connected through a via hole, ~~characterized in that~~
wherein if a thickness of the conductor layer on said core substrate is α_1 and a
thickness of the conductor layer on the interlayer insulating layer is α_2 , α_1 and α_2 satisfy α_2
 $< \alpha_1 \leq 40\alpha_2$.

Claim 3 (Currently Amended): The multilayer printed wiring board according to
claim 1, ~~characterized in that~~ wherein said α_1 satisfies $2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$.

Claim 4 (Currently Amended): The multilayer printed wiring board according to ~~any~~
~~one of claims 1 to 3~~ claim 1, ~~characterized in that~~ wherein the conductor layer of said core
substrate is the conductor layer for a power supply layer or the conductor layer for an earth.

Claim 5 (Currently Amended): The multilayer printed wiring board according to ~~any one of claims 1 to 4~~ claim 1, ~~characterized in that~~ wherein a capacitor is mounted on a surface of the multilayer printed wiring board.

Claim 6 (Currently Amended): A multilayer printed wiring board ~~having~~ comprising:
an interlayer insulating layer and a conductor layer formed on a core substrate, the conductor layer being electrically connected through a via hole, ~~characterized in that~~
wherein said core substrate is a multilayer core substrate comprising not less than three layers including a thick conductor layer as an inner layer; and
the conductor layer as the inner layer and the conductor layer on a surface of said core substrate are the conductor layers for a power supply layer or the conductor layers for an earth.

Claim 7 (Currently Amended): A multilayer printed wiring board ~~having~~ comprising:
an interlayer insulating layer and a conductor layer formed on a core substrate, the conductor layer being electrically connected through a via hole, ~~characterized in that~~
wherein said core substrate is a multilayer core substrate comprising not less than three layers including a thick conductor layer as an inner layer; and
a conductor layer as an inner layer of said core substrate is the conductor layer as a power supply layer or the conductor layer as an earth and that a conductor layer on a surface layer of said core substrate comprises a signal line.

Claim 8 (Currently Amended): A multilayer printed wiring board according to claim 6 ~~or 7~~, ~~characterized in that~~

wherein a thickness of the conductor layer on said core substrate is larger than a thickness of the conductor layer on the interlayer insulating layer.

Claim 9 (Currently Amended): The multilayer printed wiring board according to claim 6 ~~or 7, characterized in that~~ wherein the conductor layer as the inner layer of said core substrate is not less than two conductor layers.

Claim 10 (Currently Amended): The multilayer printed wiring board according to claim 6 ~~or 7, characterized in that~~ wherein said core substrate is constituted so that the conductor layer as said inner layer is formed on each surface of an electrically isolated metallic plate through a resin layer and so that said conductor layer on the surface layer is formed outside of the conductor layer as the inner layer through the resin layer.

Claim 11 (Currently Amended): The multilayer printed wiring board according to claim 6 ~~or 7, characterized in that~~ wherein said core substrate comprises a thick conductor layer as the inner layer and a thin conductor layer as the conductor layer on the surface layer.

Claim 12 (New): The multilayer printed wiring board according to claim 2, wherein the conductor layer of said core substrate is the conductor layer for a power supply layer or the conductor layer for an earth.

Claim 13 (New): The multilayer printed wiring board according to claim 2, wherein a capacitor is mounted on a surface of the multilayer printed wiring board.

Claim 14 (New): A multilayer printed wiring board according to claim 7,
wherein a thickness of the conductor layer on said core substrate is larger than a
thickness of the conductor layer on the interlayer insulating layer.

Claim 15 (New): The multilayer printed wiring board according to claim 7, wherein
the conductor layer as the inner layer of said core substrate is not less than two conductor
layers.

Claim 16 (New): The multilayer printed wiring board according to claim 7, wherein
said core substrate is constituted so that the conductor layer as said inner layer is formed on
each surface of an electrically isolated metallic plate through a resin layer and so that said
conductor layer on the surface layer is formed outside of the conductor layer as the inner
layer through the resin layer.

Claim 17 (New): The multilayer printed wiring board according to claim 7, wherein
said core substrate comprises a thick conductor layer as the inner layer and a thin conductor
layer as the conductor layer on the surface layer.